

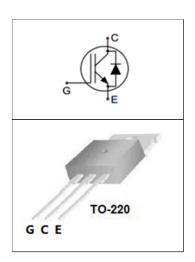
#### **IGBT**

#### **Features**

- 650V,15A
- $V_{CE(sat)(typ.)}=1.9V@V_{GE}=15V,I_{C}=15A$
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA



JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as Motor control, general inverter and other soft switching applications.



#### **Absolute Maximum Ratings**

Symbol	Parameter	Value	Units
Vces	Collector-Emitter Voltage	650	V
V <sub>GES</sub>	Gate-Emitter Voltage	<u>+</u> 30	V
	Continuous Collector Current ( Tc=25 °C)	30	Α
lc	Continuous Collector Current (Tc=100°C)	15	Α
Ісм	Pulsed Collector Current (Note 1)	45	Α
I <sub>F</sub>	Diode Continuous Forward Current ( T <sub>C</sub> =100 °C)	15	Α
I <sub>FM</sub>	Diode Maximum Forward Current (Note 1)	45	Α
t <sub>sc</sub>	Short Circuit Withstand Time	10	us
Б	Maximum Power Dissipation ( T <sub>C</sub> =25 °C)	104	W
P <sub>D</sub>	Maximum Power Dissipation ( T <sub>C</sub> =100 °C)	41.7	W
TJ	Operating Junction Temperature Range	-55 to +150	$^{\circ}$
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	$^{\circ}$ C

## **Thermal Characteristics**

Symbol	Parameter	Max.	Units
R <sub>th j-c</sub>	Thermal Resistance, Junction to case for IGBT	1.2	°C/ <b>W</b>
R <sub>th j-c</sub>	Thermal Resistance, Junction to case for Diode	2.5	°C/W
R <sub>th j-a</sub>	Thermal Resistance, Junction to Ambient	62	°C/W



## **Electrical Characteristics** (Tc=25 °C unless otherwise noted )

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE}$ = 0V, $I_{C}$ = 250uA	650	-	-	V
I <sub>CES</sub>	Collector-Emitter Leakage Current	V <sub>CE</sub> = 650V, V <sub>GE</sub> = 0V	-	-	100	uA
I <sub>GES</sub>	Gate Leakage Current, Forward	$V_{GE}$ = $\pm 20$ V, $V_{CE}$ = $0$ V	-	-	±100	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$ , $I_{C} = 250uA$	4.5	-	6.5	V
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	V <sub>GE</sub> =15V, I <sub>C</sub> = 15A	-	1.9	2.5	V
Qg	Total Gate Charge	Vcc=480V	-	40.7		nC
Qge	Gate-Emitter Charge	V <sub>GE</sub> =15V	-	4.19		nC
Qgc	Gate-Collector Charge	Ic=15A	-	30.7		nC
t d(on)	Turn-on Delay Time	V <sub>CC</sub> =400V V <sub>GE</sub> =15V I <sub>C</sub> =15A R <sub>G</sub> =15Ω	-	16	-	ns
t r	Turn-on Rise Time		-	20	-	ns
t d(off)	Turn-off Delay Time		-	94	-	ns
t f	Turn-off Fall Time		-	118	-	ns
Eon	Turn-on Switching Loss	Inductive Load	-	0.31	-	mJ
Eoff	Turn-off Switching Loss	T <sub>C</sub> =25 ℃	-	0.32	-	mJ
Ets	Total Switching Loss		-	0.63	-	mJ
C <sub>ies</sub>	Input Capacitance	V <sub>CE</sub> =25V V <sub>GE</sub> =0V	-	629	-	pF
Coes	Output Capacitance		-	45	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1MHz	-	7	-	pF

## **Electrical Characteristics of Diode** (Tc=25°C unless otherwise noted )

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> =15A	-	1.55	3.0	V
trr	Diode Reverse Recovery Time	V <sub>CE</sub> = 400V	-	120		ns
Irr	Diode peak Reverse Recovery Current	I <sub>F</sub> = 15A	-	17.5		Α
Q <sub>r r</sub>	Diode Reverse Recovery Charge	Rg=15 Ω	-	690		nC

#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature



## **Typical Performance Characteristics**

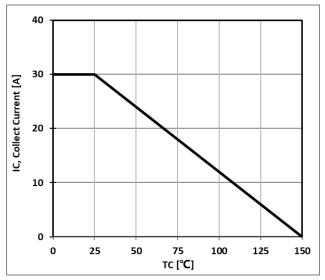


Figure 1: Maximum DC Collector Current VS. case temprature

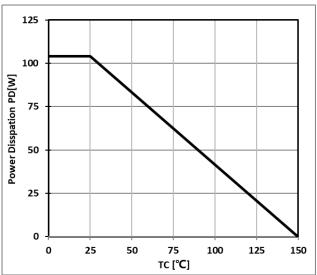


Figure 2: Power Dissipation VS. Case Temperature

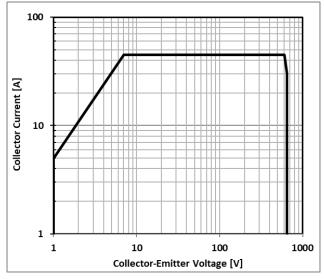


Figure 3: Reverse Bias SOA,TJ=125℃,VGE=15V

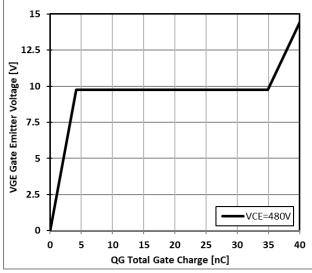


Figure 4: Typical Gate charge VS. VGE,IC=15A



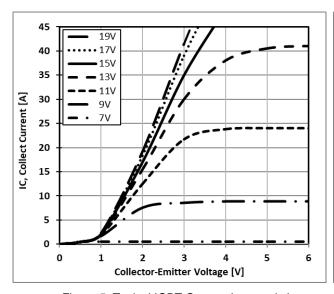


Figure 5: Typical IGBT Output characteristics,  $TC=25^{\circ}C$ ;tp=300us

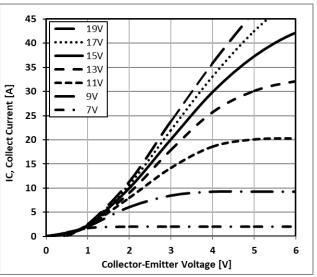


Figure 6: Typical IGBT Output characteristics, TC=150°C;tp=300us

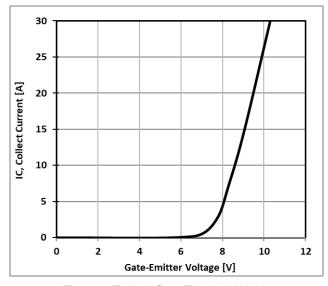


Figure 7: Typical Gate Threshold Voltage

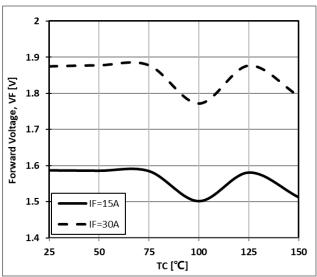


Figure 8: Typical Forward Voltage vs IF



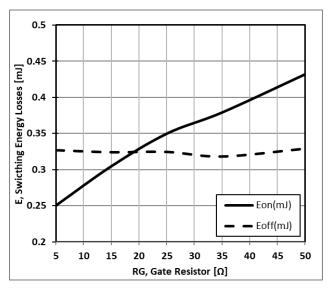


Figure 9: Typical Energy Loss VS. RG, TC=25°C, L=200uH,VCE=400V,VGE=15V,IC=15A

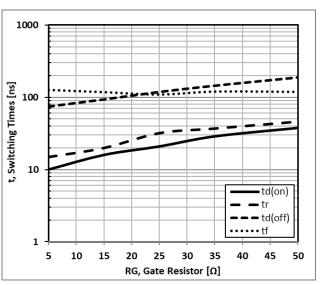


Figure 10: Typical Switching Time VS. RG, TC=25°C, L=200uH,VCE=400V,VGE=15V,IC=15A

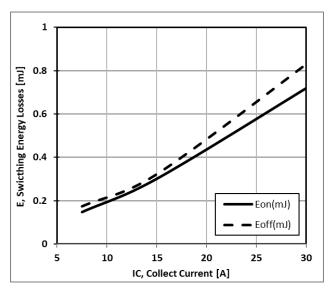


Figure 11: Typical Energy Loss VS. IC,TC=25 $^{\circ}$ C, L=200uH,VCE=400V,VGE=15V,RG=15 $^{\circ}$ 

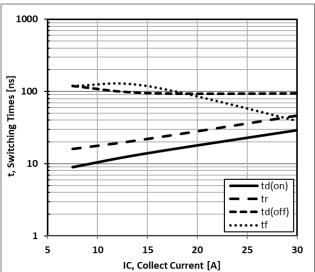


Figure 12: Typical Switching Time VS. IC,TC=25 $^{\circ}$ C, L=200uH,VCE=400V,VGE=15V,RG=15 $^{\circ}$ 



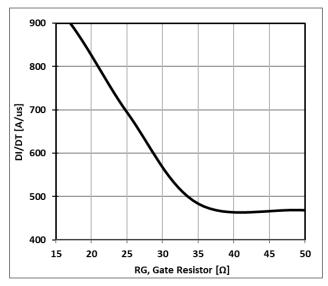


Figure 13: Typical Diode DI/DT VS. RG,TC=25°C VCC=400V, VGE=15V, IF=15A

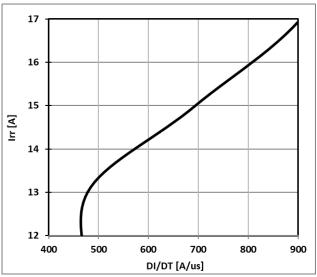


Figure 14: Typical Diode IRR VS. DI/DT,TC=25°C VCC=400V, VGE=15V, IF=15A

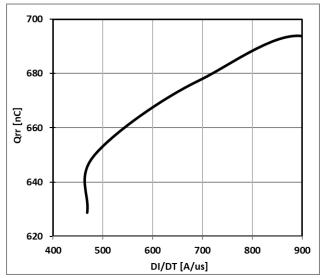


Figure 15: Typical Diode Qrr VS. DI/DT,TC=25℃ VCC=400V, VGE=15V, IF=15A

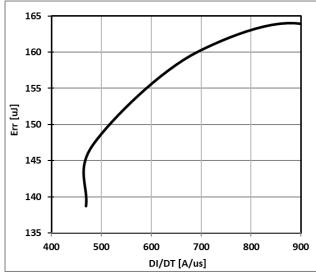
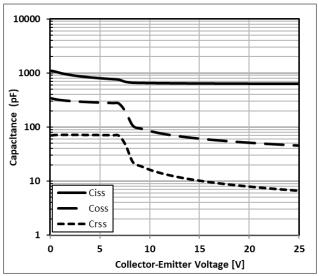


Figure 16: Typical Diode Err VS. DI/DT,TC=25℃ VCC=400V, VGE=15V, IF=15A





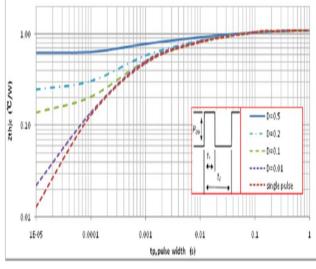
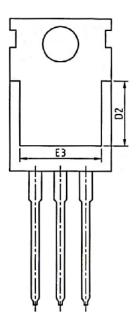


Figure 17: Typical Capacitance VS. VCE, VGE=0V,f=1MHz

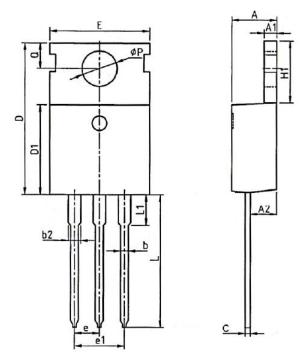
Figure 18: Normalized transient thermal impedance junction-to-case



#### **TO-220C PACKAGE OUTLINE**



SYMBOL	MIN	NOM	MAX	
Α	4.37	4.57	4.7	
A1	1.25	1.3	1.4	
A2	2.2	2.4	2.6	
Ь	0.7	0.8	0.95	
b2	1.17	1.27	1.47	
C	0.45	0.5	0.6	
D	15.1	15.6	16.1	
D1	8.8	9.1	9.4	
D2	5.5	-	-	
Е	9.7	10	10.3	
E3	7	-	-	
е	2.54 BSC			
e1	5.08 BSC			
H1	6.25	6.5	6.85	
L	12.75	13.5	13.8	
L1	-	3.1	3.4	
ФР	3.4	3.6	3.8	
Q	2.6	2.8	3	





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